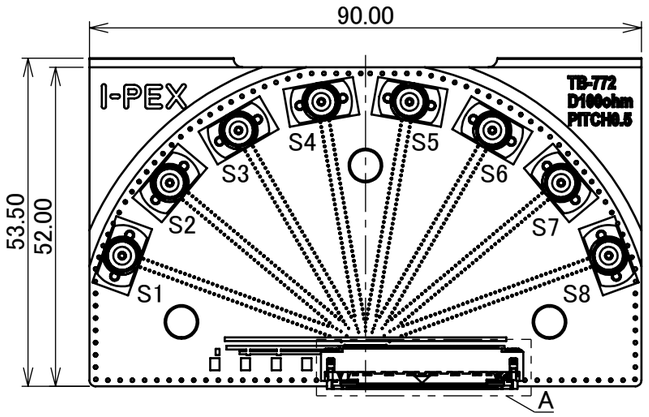
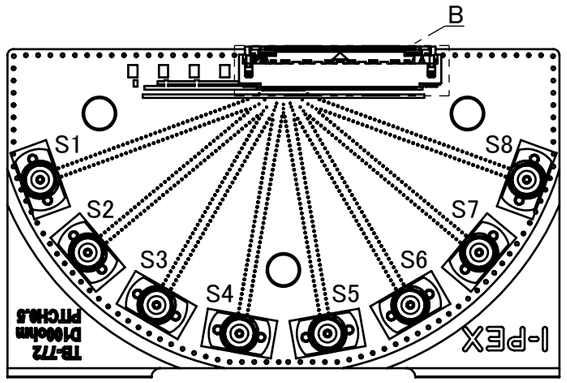
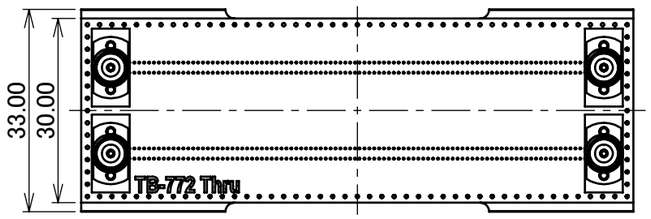
PART NO.	STRUCTURE
91572-0**B-001	MAIN BOARD A ASSEMBLY: 1PC MAIN BOARD B ASSEMBLY: 1PC 2xTHRU BOARD: 1PC



MAIN BOARD A ASSEMBLY

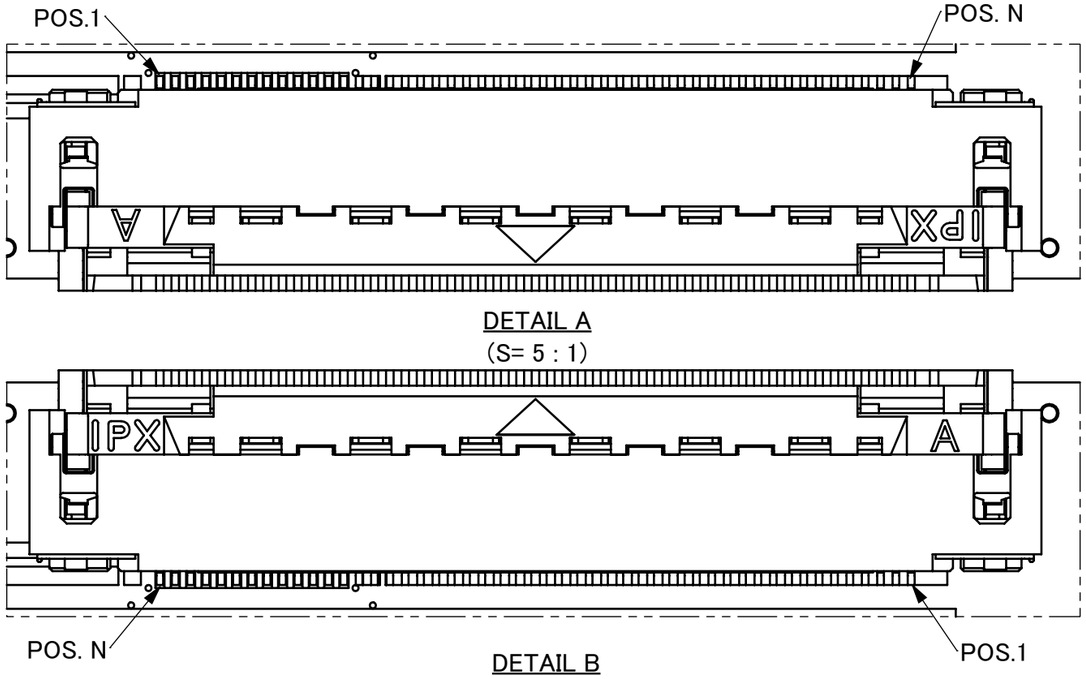


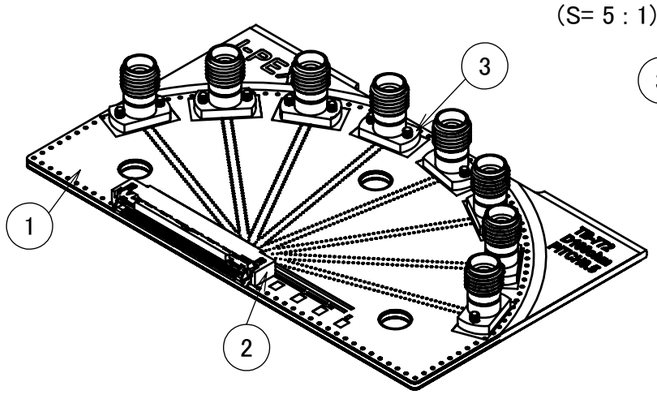
MAIN BOARD B ASSEMBLY



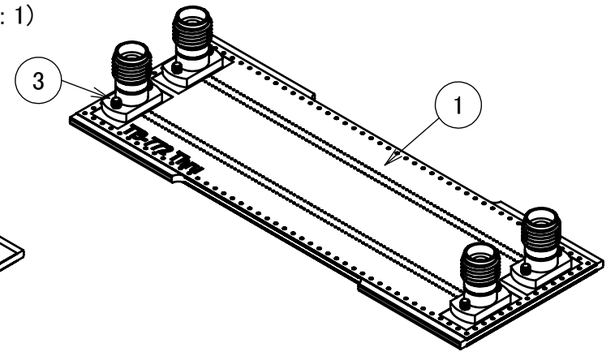
2xTHRU BOARD ASSEMBLY

91572-0**B-001
└ POS. 30, 50





MAIN BOARD A/B ASSEMBLY



2xTHRU BOARD ASSEMBLY

MAIN BOARD A	
PIN POS.	ASSIGNMENT
1	GND
2	S1
3	S2
4	GND
5	S3
6	S4
7	GND
8	S5
9	S6
10	GND
11	S7
12	S8
13	GND

MAIN BOARD B	
PIN POS.	ASSIGNMENT
N	GND
N-1	S1
N-2	S2
N-3	GND
N-4	S3
N-5	S4
N-6	GND
N-7	S5
N-8	S6
N-9	GND
N-10	S7
N-11	S8
N-12	GND

NO.	DESCRIPTION	PART NO.	QTY	REMARKS
3	2.92mm CONNECTOR	50104-J001	20	JACK
2	CONNECTOR	20899-0**E-01	2	EVAFLEX 5-SE-G HT RECEPTACLE
1	TEST BOARD	TB-772	1	TEST BOARD THICKNESS: 1.60mm

NOTES.
1. FOR DETAILED INFORMATION ON THE STRUCTURE OF TEST BOARD TB-772, REFER TO REPORT #IER-001-10705.
2. CHARACTERISTIC IMPEDANCE: 50 Ω ± 10 % (SINGLE-ENDED), Tr=17.5 ps (10 % - 90 %)
3. REFERENCE FFC: SEE DRAWING OF EVAFLEX 5-SE-G HT (P/N: 20899)
4. MAXIMUM MEASUREMENT FREQUENCY: 40 GHz
5. OTHER PIN CONFIGURATIONS CAN BE PROVIDED UPON REQUEST.

REV.	ECN	BY	DATE	APP.
0	Z241141	T.O	2024/08/28	

REVISION RECORD

ANGLE	±2°	6 OVER 30 MAX.	±0.3
6 MAX.	±0.2	30 OVER 120 MAX.	±0.5

GENERAL TOLERANCE.

PROJECTION | SERIES No. R2R4R0

CUSTOMER COPY

DWG. T.Onishi DATE 2024/08/28

CHK. M.Muro

APP. T.Masunaga

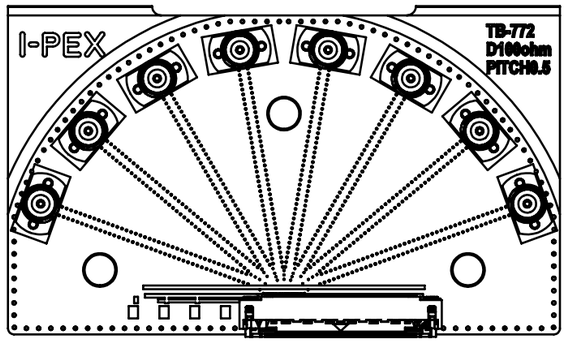
TITLE: EVAFLEX® 5-SE-G HT SI TEST BOARD ASSEMBLY

DWG. No. 91572

SCALE 1:1 | UNIT mm | SIZE A3 | SHEET 1/2 | REV. 0

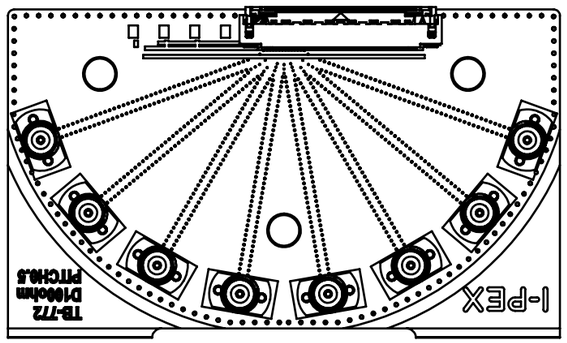
I-PEX

Confidential C



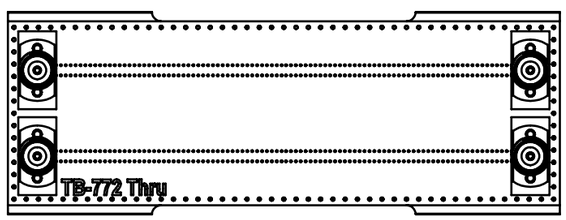
MAIN BOARD A ASSEMBLY

<SMALL BAG>
REUSABLE PLASTIC BAG



MAIN BOARD B ASSEMBLY

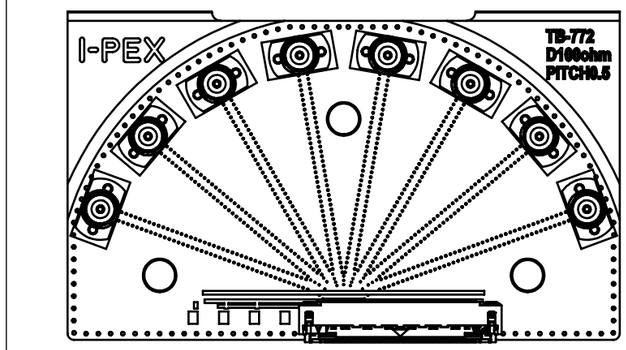
<SMALL BAG>
REUSABLE PLASTIC BAG

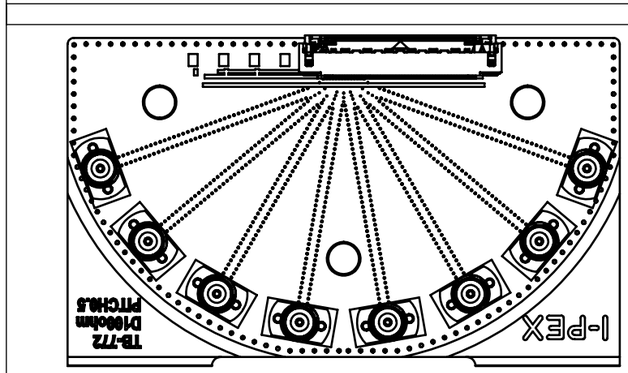


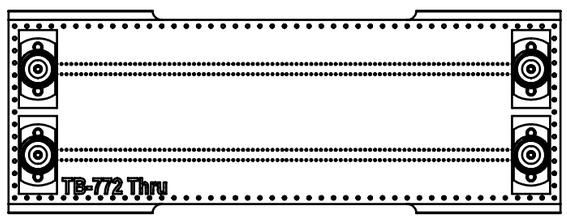
2xTHRU BOARD ASSEMBLY

<SMALL BAG>
REUSABLE PLASTIC BAG

<LARGE BAG>
REUSABLE PLASTIC BAG







PACKING STYLE

ANGLE	±2°	6 OVER 30 MAX.	±0.3	PROJECTION	SERIES No.	CUSTOMER COPY	
6 MAX.	±0.2	30 OVER 120 MAX.	±0.5		R2R4R0		
GENERAL TOLERANCE.				TITLE		SCALE	
DWG.		DATE		EVAFLEX® 5-SE-G HT SI TEST BOARD ASSEMBLY		1:1	I-PEX
CHK.						UNIT mm	
APP.				DWG. No. 91572		SIZE A3	SHEET 2/2 REV. 0